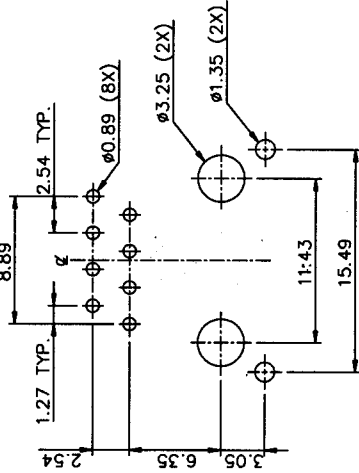
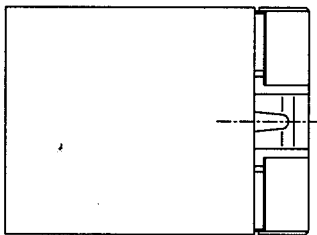
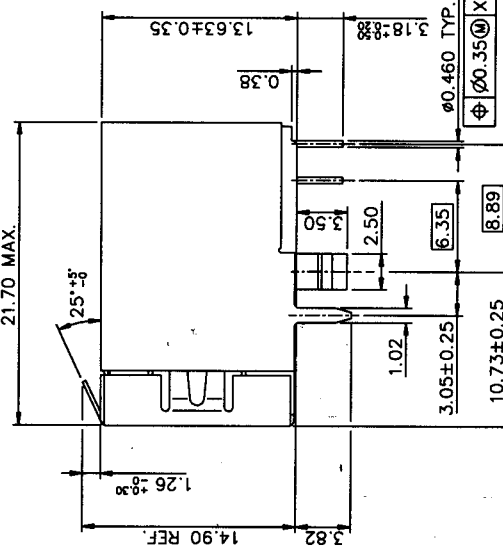
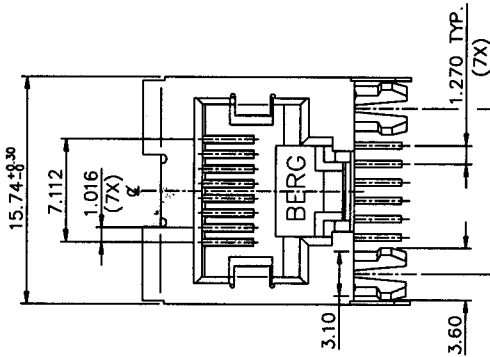


PRODUCT NO.
74523-00IN
-00INLE

LEAD FREE PRODUCT NO.



RECOMMENDED PCB LAYOUT



- NOTES:
1. RECOMMENDED P.C.B THICKNESS 1.60 MM
 2. HOUSING MAT'L: HIGH TEMP RESIN.
 3. CONTACTS: PHOS BRONZE ALLOY UNS-C51000, 90.460 ROUND WIRE, PLATING SEE TABLE.
 4. SHIELDING MATERIAL: 0.25MM THICK, COPPER ALLOY. SHIELDING PLATING: 30µ" MIN. NICKEL PLATED.
 5. PACKAGING: USING TRAY.
 6. PART NO. DESCRIPTIONS:
74523 - X 01 N
SHIELDING PLATING:
FOR 30µ" NICKEL PLATING ONLY.
PORT NUMBERS
PLATING CODE:
0=0.76µm/30µ" GXT
 7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-00B.
 8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD.
 9. IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.

| mat'l code | | tolerance unless otherwise specified | | CUSTOMER COPY | | FCJ | |
|------------|----------|--------------------------------------|----------|---------------|------------|---|--------------------|
| rev | ecr no | dr | date | linear | projection | title | www.fcjconnect.com |
| A | 180318 | am | 07/21/98 | .00 ± 0.15 | 0.30 | R/A CAT 5 MOD JACK 8 POS. SPECIALLY SHIELDED SNAP PEG | |
| B | 103-0443 | vl | 10/06/03 | .000 ± 0.10 | 0.15 | SPECIALY SHIELDED SNAP PEG | |
| C | 105-0002 | ys | 07/11/05 | angles ± 2' | 0.30 | product family | M00 JACK |
| D | 105-0018 | ys | 01/21/05 | dr | unit | size | mm/inch |
| | | | | engr | TONY CHIEN | 12/03/97 | code |
| | | | | chr | TONY CHIEN | 12/03/97 | sheet |
| | | | | appd | JENN TSAO | 12/03/97 | 1 of 1 |
| sheet | revision | D | | scale | 3 : 1 | A.3 | 74523 |
| index | sheet | 1 | | | | | 1 of 1 |

1 2 3 4 5 6